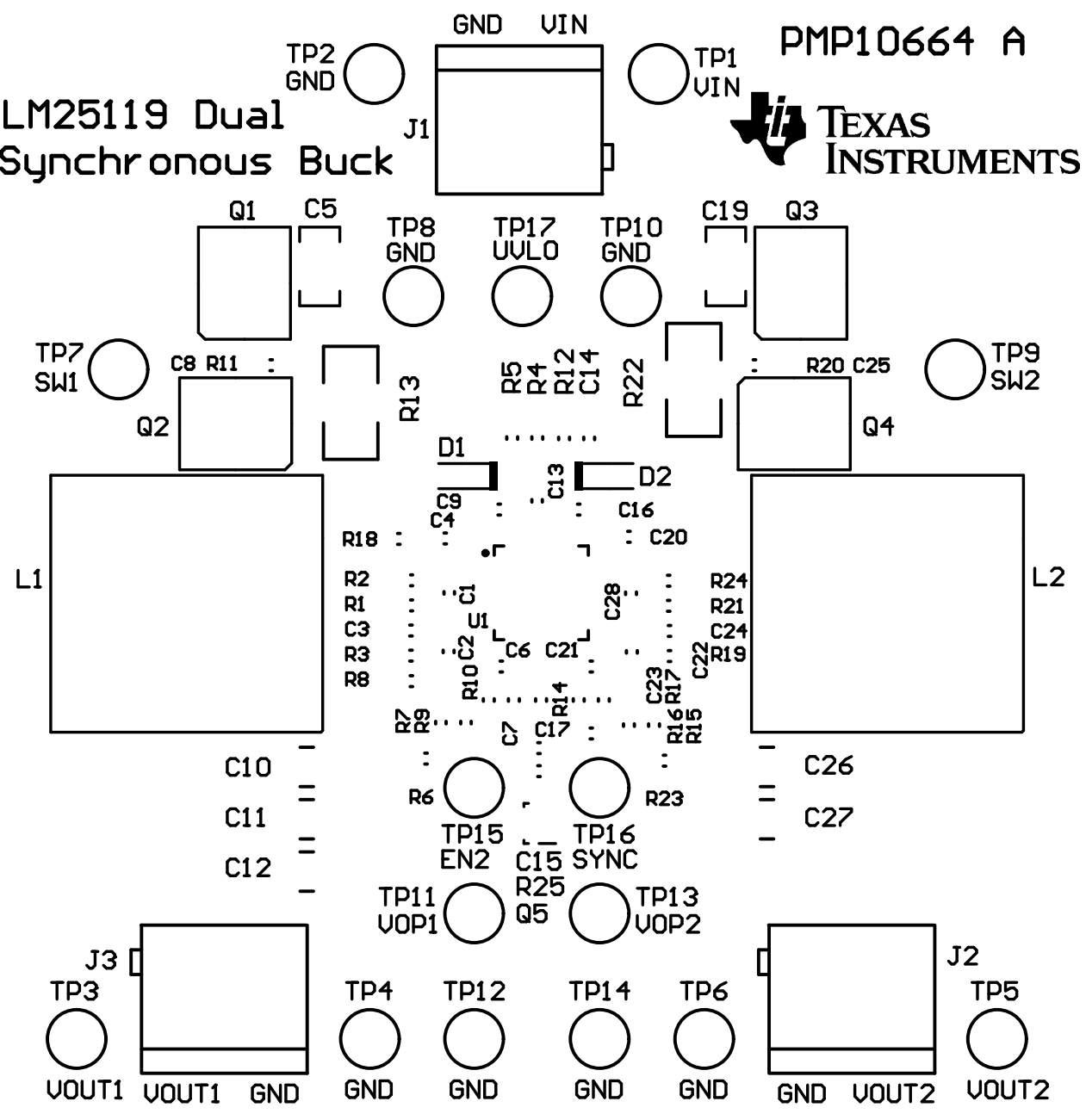


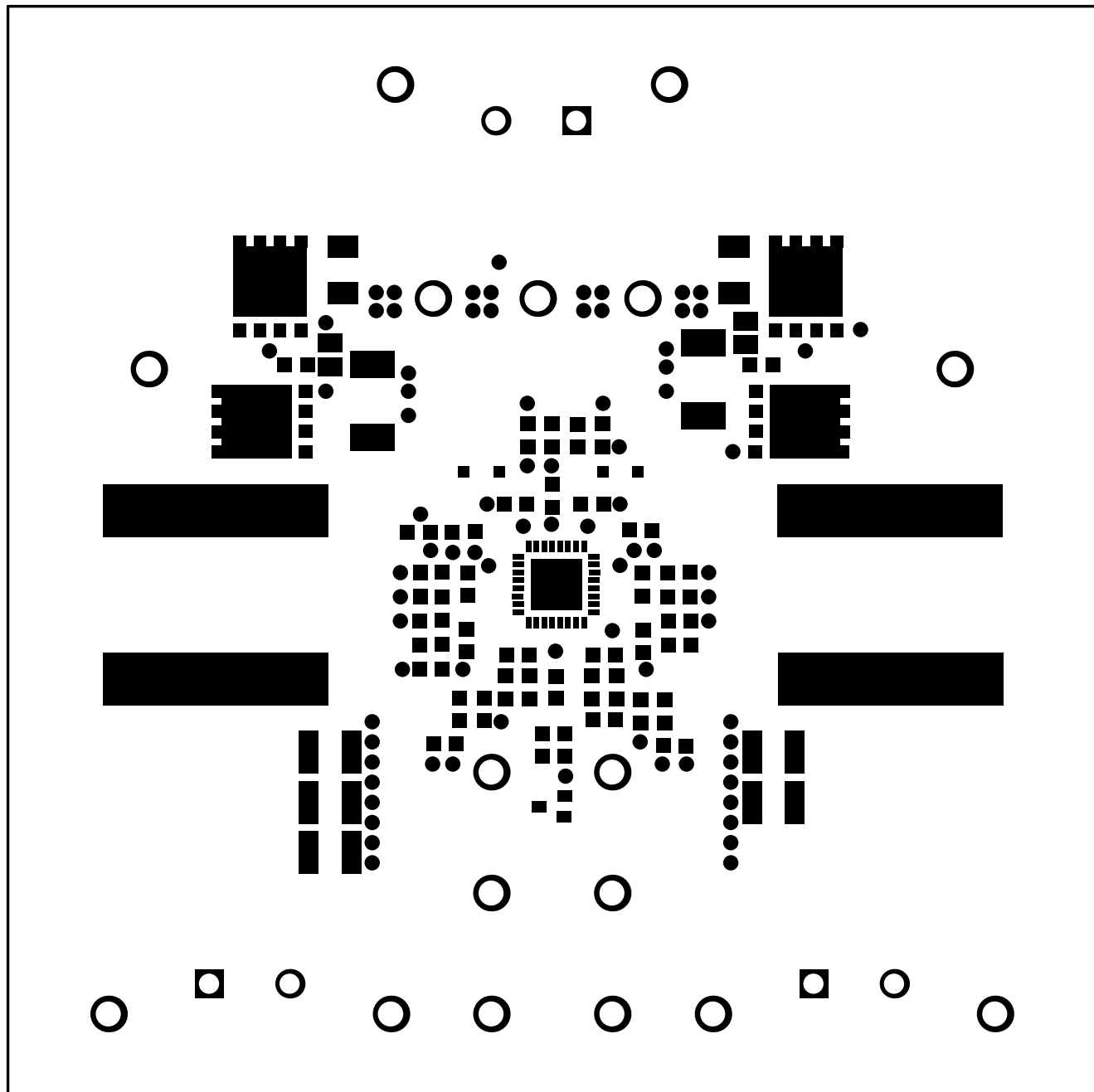
LM25119 Dual Synchronous Buck

PMP10664 A

TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10664	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: PMP10664		
PLOT NAME = Top Overlay	GENERATED : 6/1/2015	10:43:58 AM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE

BOARD #: PMP10664

REV: A

SUN REV: Not In VersionControl

LAYER NAME = Top Solder

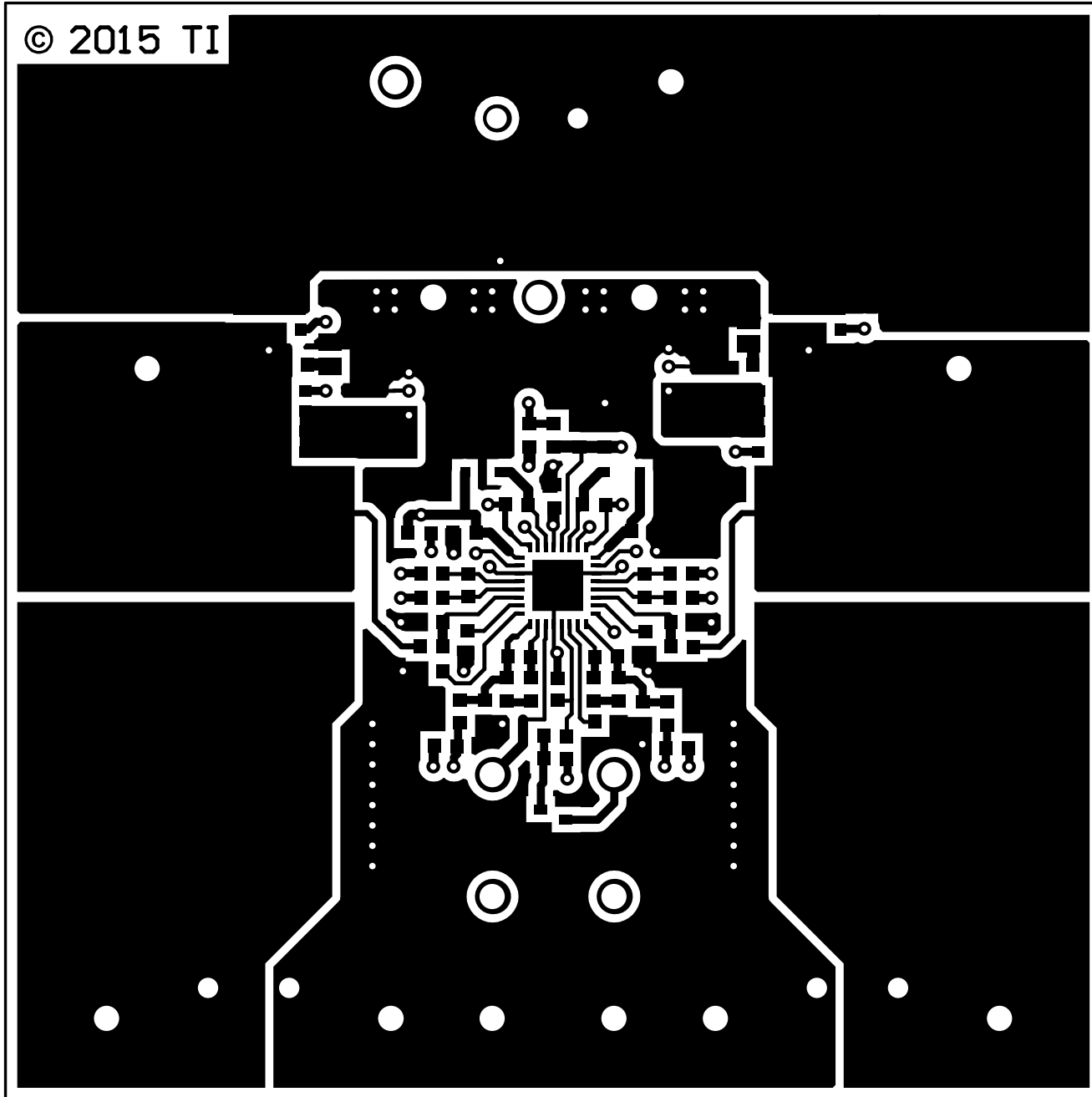
TID #: PMP10664

PLOT NAME = Top Solder Mask

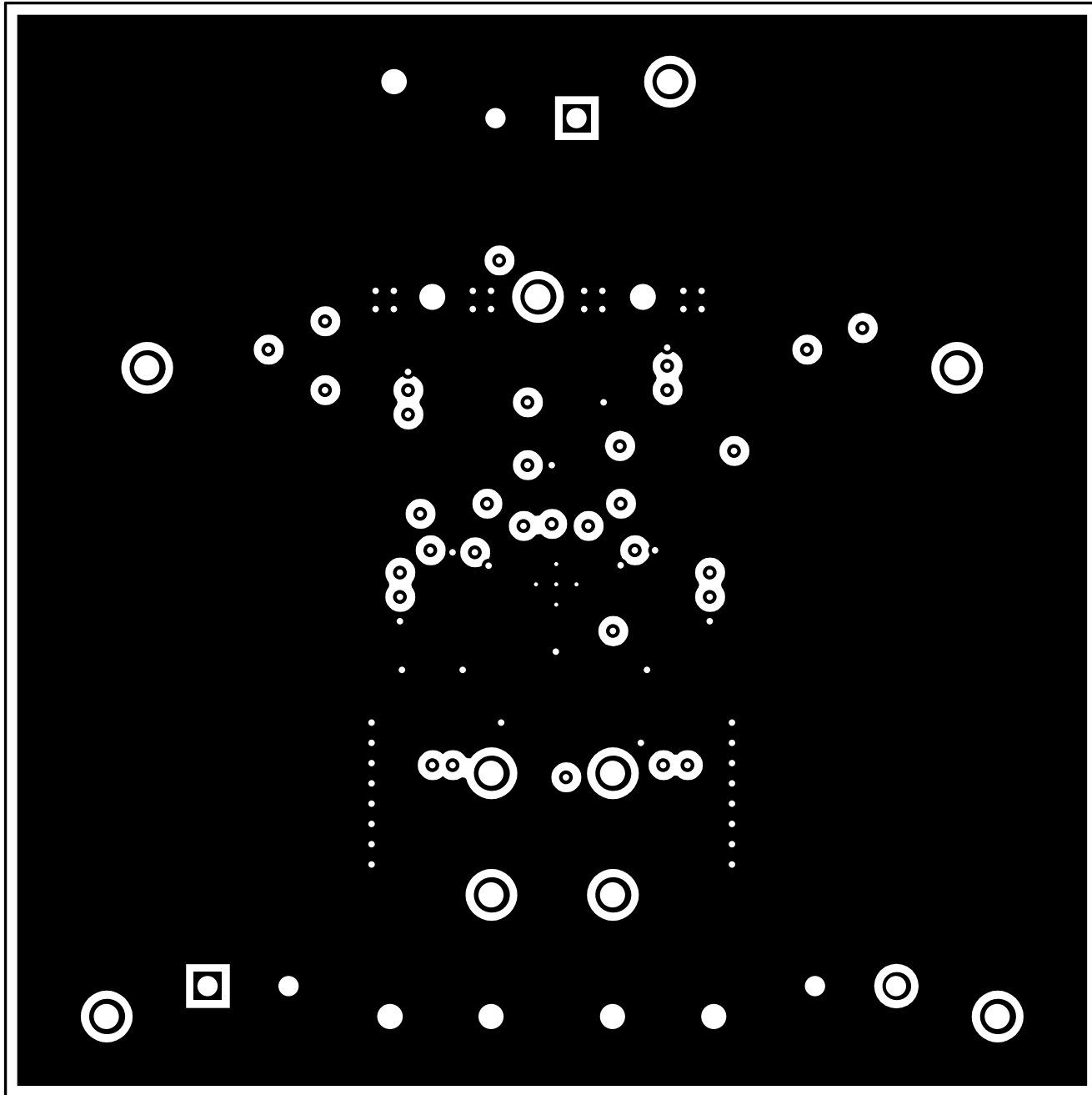
GENERATED : 6/1/2015 10:44:00 AM

TEXAS INSTRUMENTS

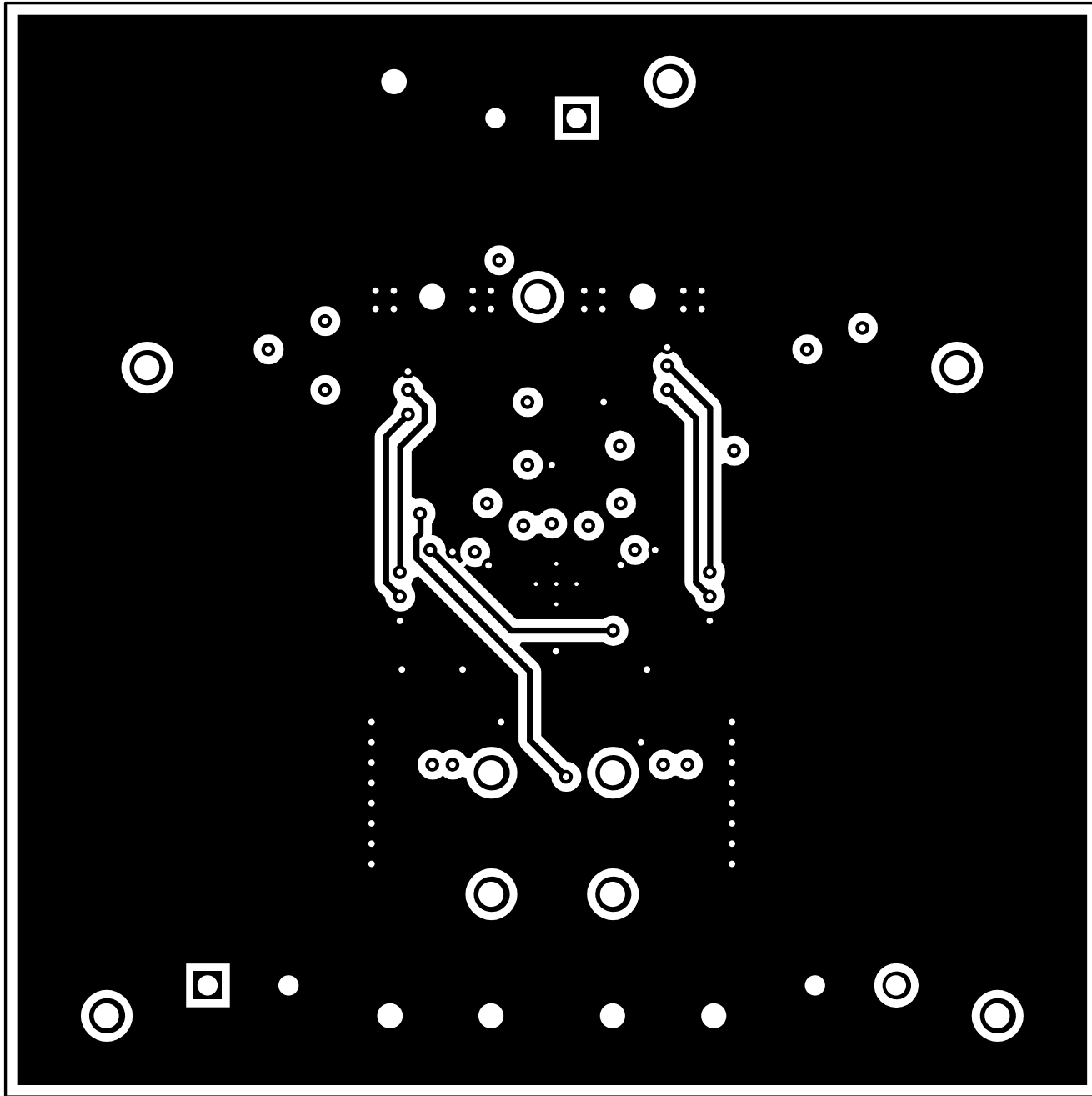
© 2015 TI



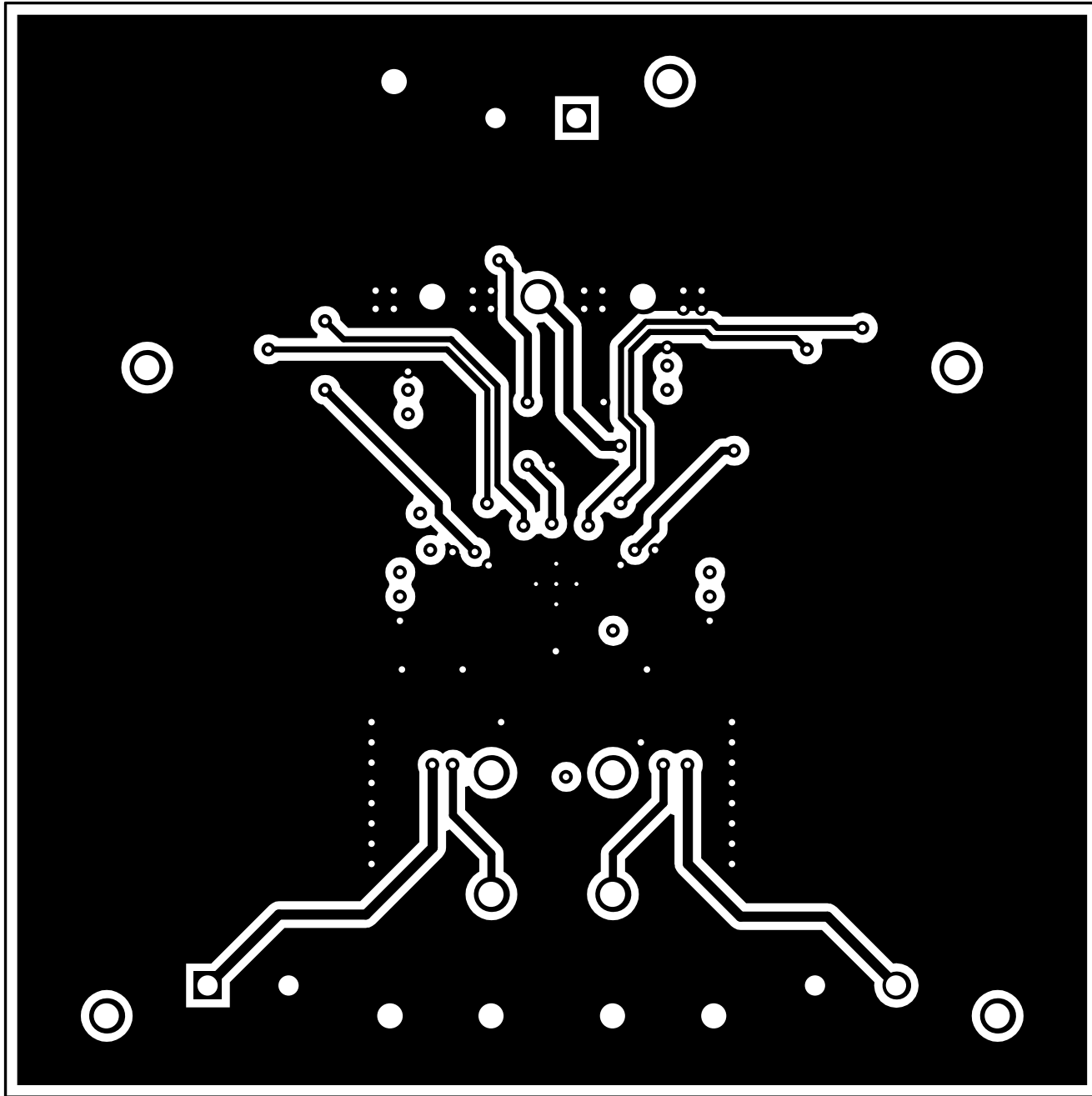
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10664	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: PMP10664		
PLOT NAME = Top Layer	GENERATED : 6/1/2015	10:44:01 AM	TEXAS INSTRUMENTS



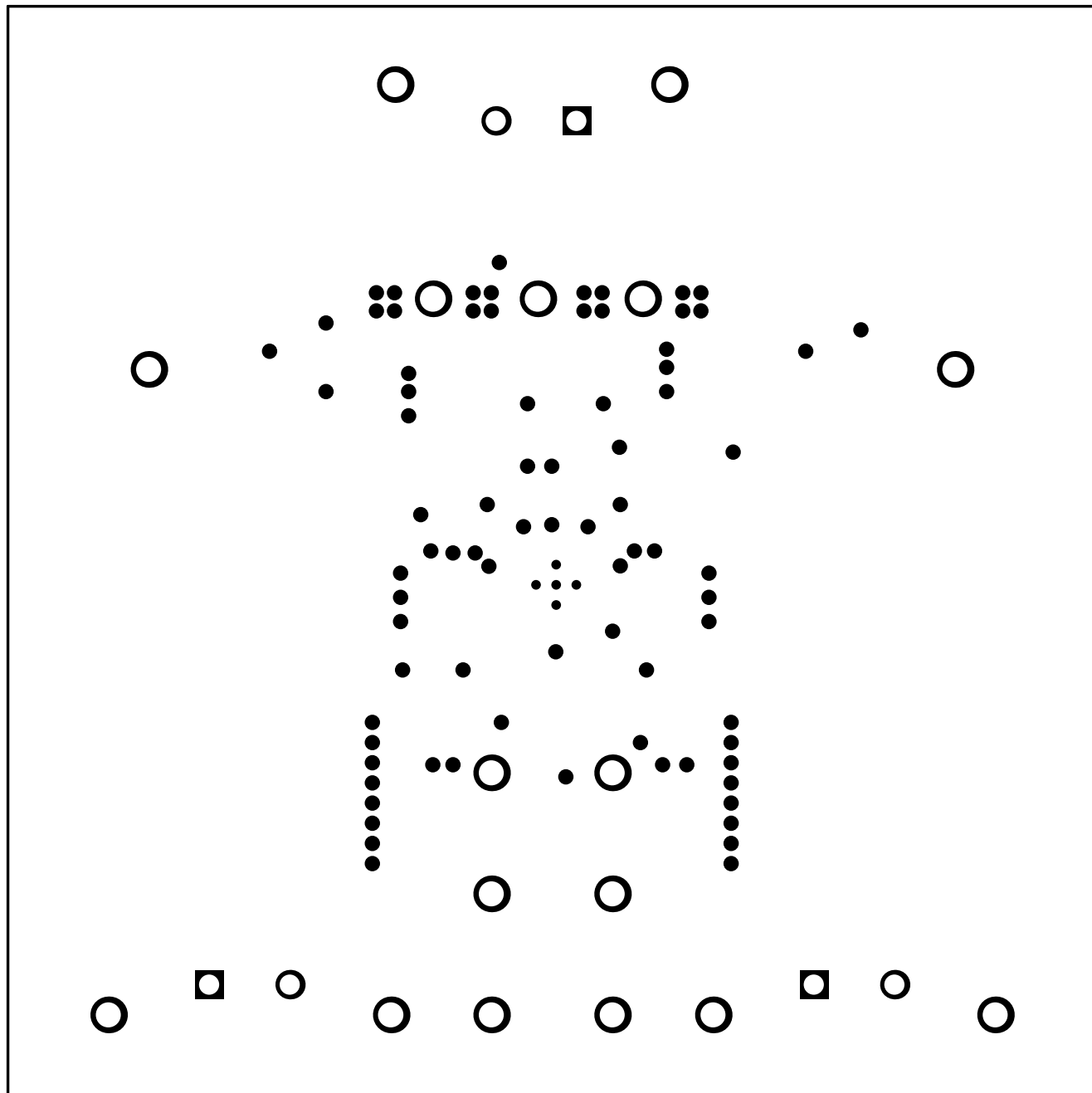
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10664	REV: A	SUN REV: Not In VersionControl
LAYER NAME =	TID #: PMP10664		
PLOT NAME = Signal Layer 1	GENERATED : 6/1/2015	10:44:02 AM	TEXAS INSTRUMENTS



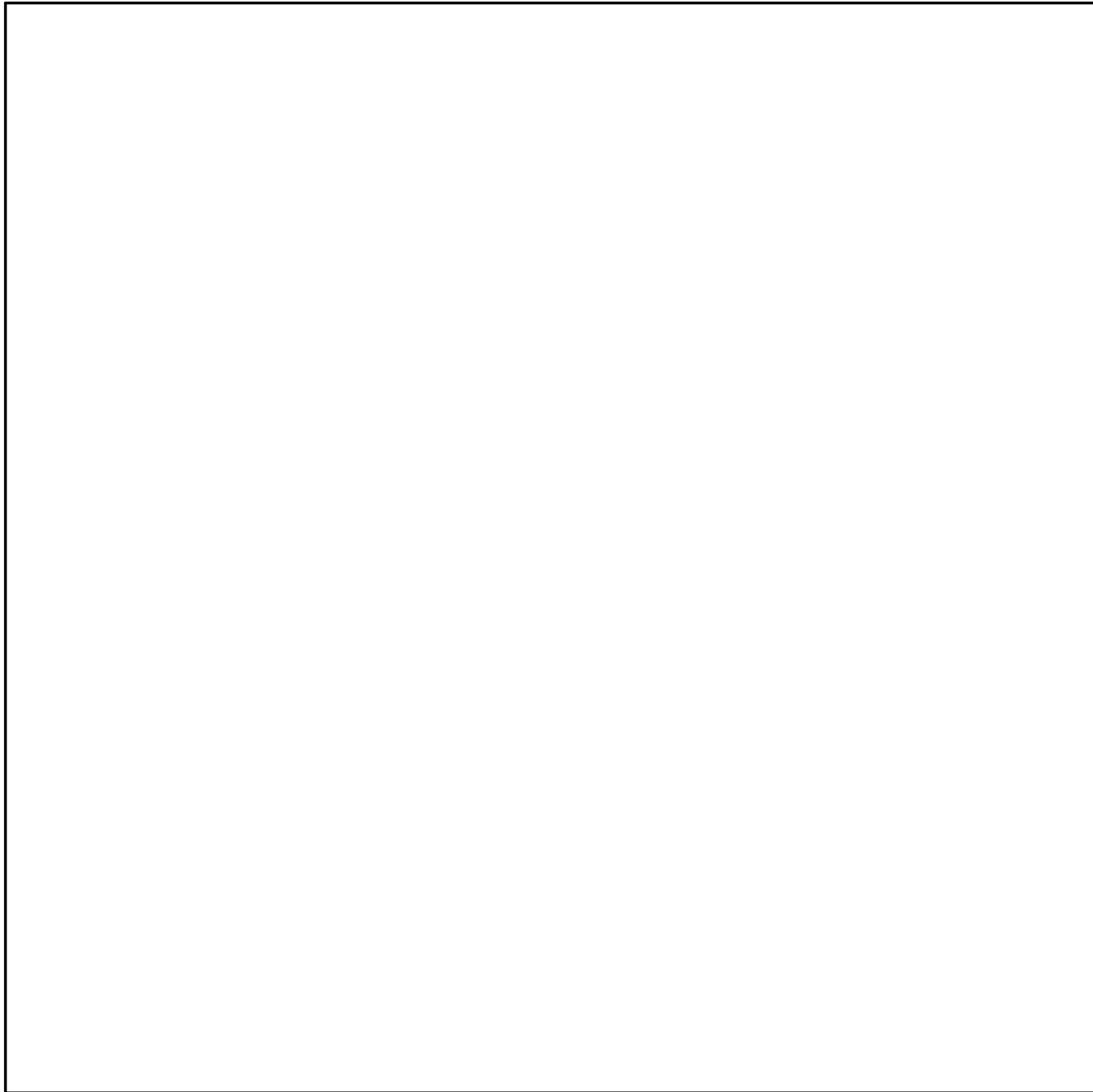
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10664	REV: A	SUN REV: Not In VersionControl
LAYER NAME =	TID #: PMP10664		
PLOT NAME = Signal Layer 2	GENERATED : 6/1/2015	10:44:03 AM	TEXAS INSTRUMENTS



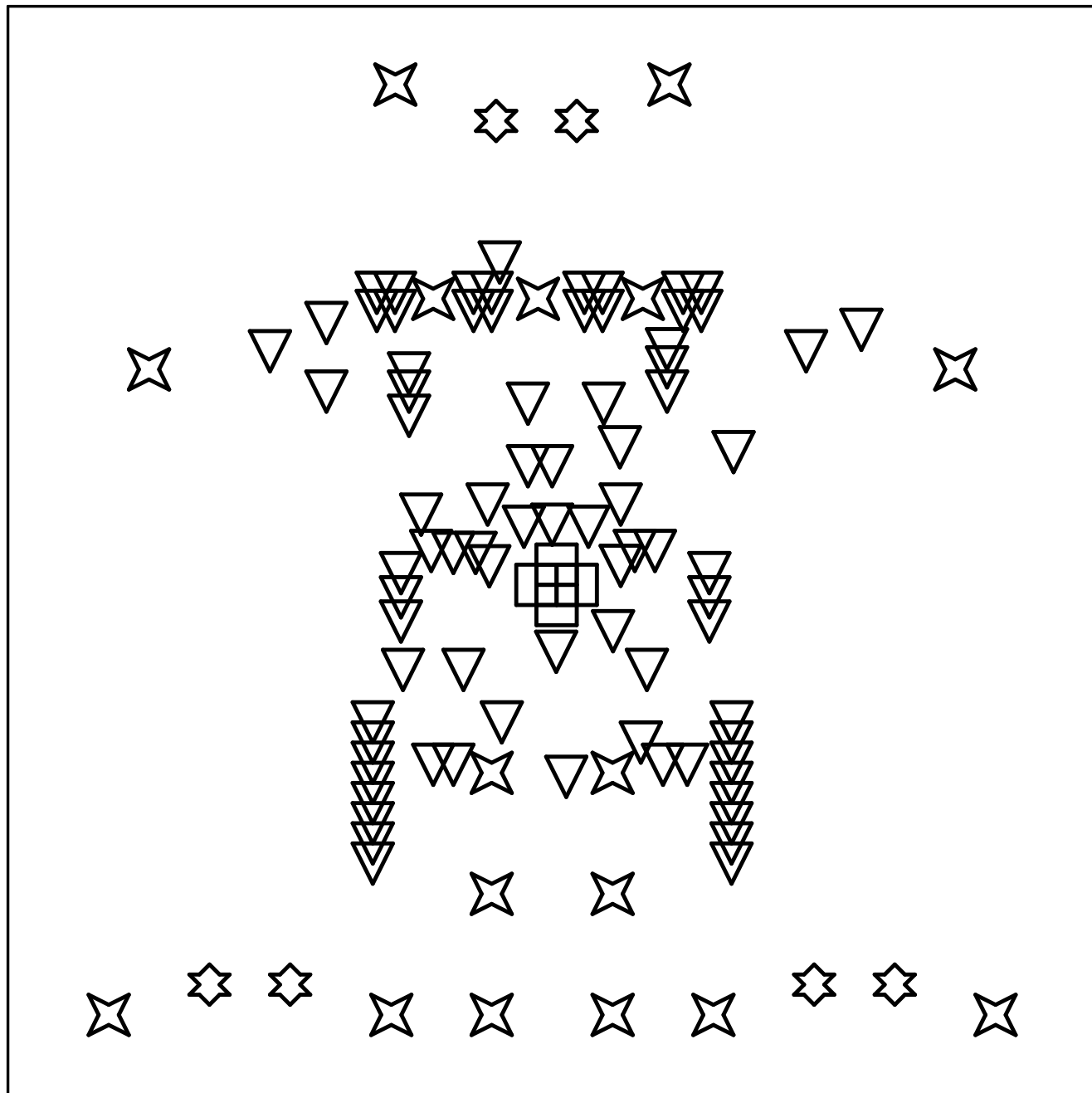
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10664	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: PMP10664		
PLOT NAME = Bottom Layer	GENERATED : 6/1/2015	10:44:04 AM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10664	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: PMP10664		
PLOT NAME = Bottom Solder Mask	GENERATED : 6/1/2015	10:44:05 AM	TEXAS INSTRUMENTS

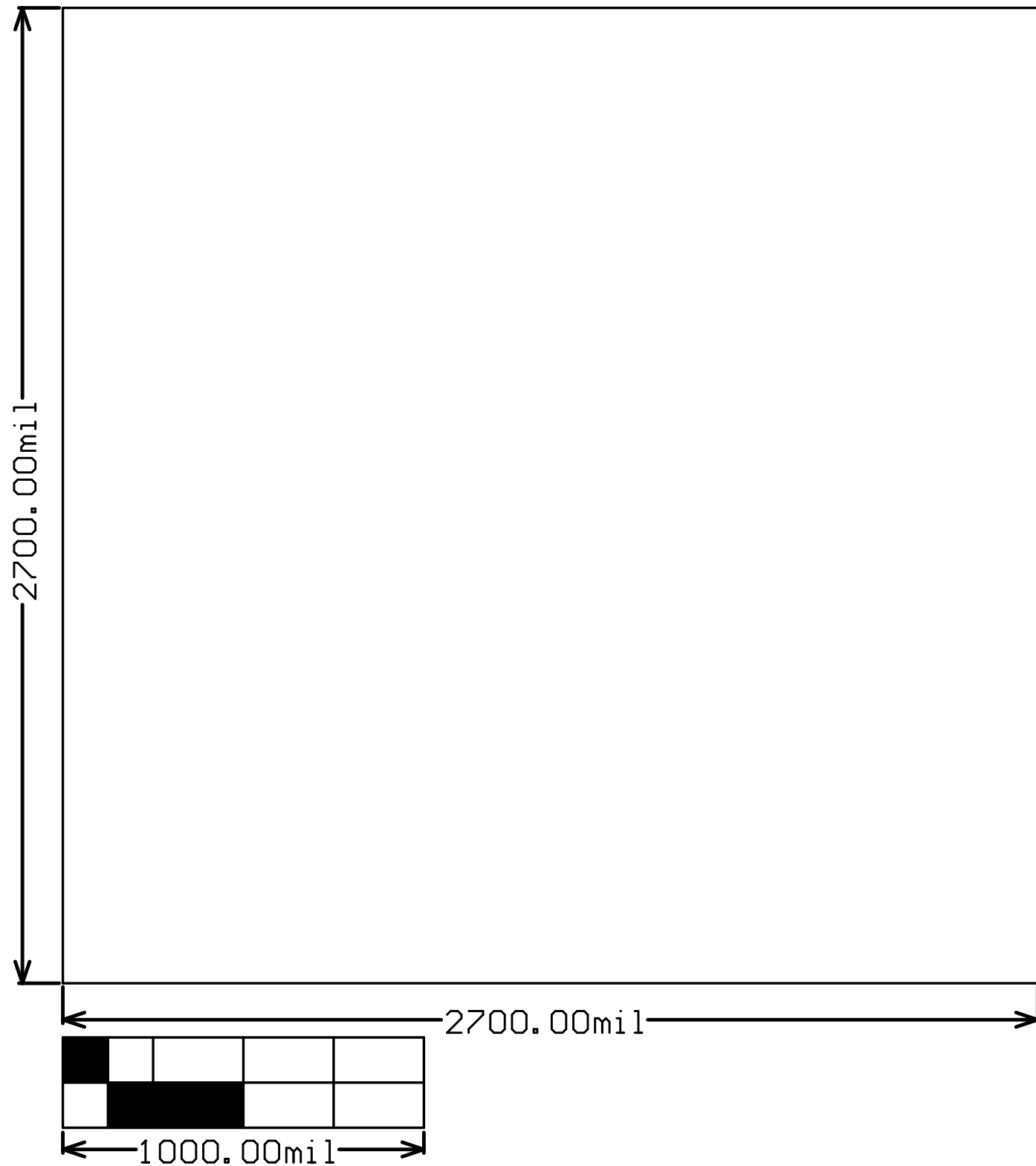


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10664	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: PMP10664		
PLOT NAME = Bottom Overlay	GENERATED : 6/1/2015	10:44:06 AM	TEXAS INSTRUMENTS



Symbol	Quantity	Finished Hole Size	Plated	Hole Type
□	5	10.00mil (0.254mm)	PTH	Round
▽	81	16.00mil (0.406mm)	PTH	Round
✳	6	49.21mil (1.250mm)	PTH	Round
✳	17	63.00mil (1.600mm)	PTH	Round
	109 Total			

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10664	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: PMP10664		
PLOT NAME = Drill Drawing	GENERATED : 6/1/2015	10:44:07 AM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10664	REV: A	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: PMP10664		
PLOT NAME = Board Dimensions	GENERATED : 6/1/2015	10:44:08 AM	TEXAS INSTRUMENTS

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